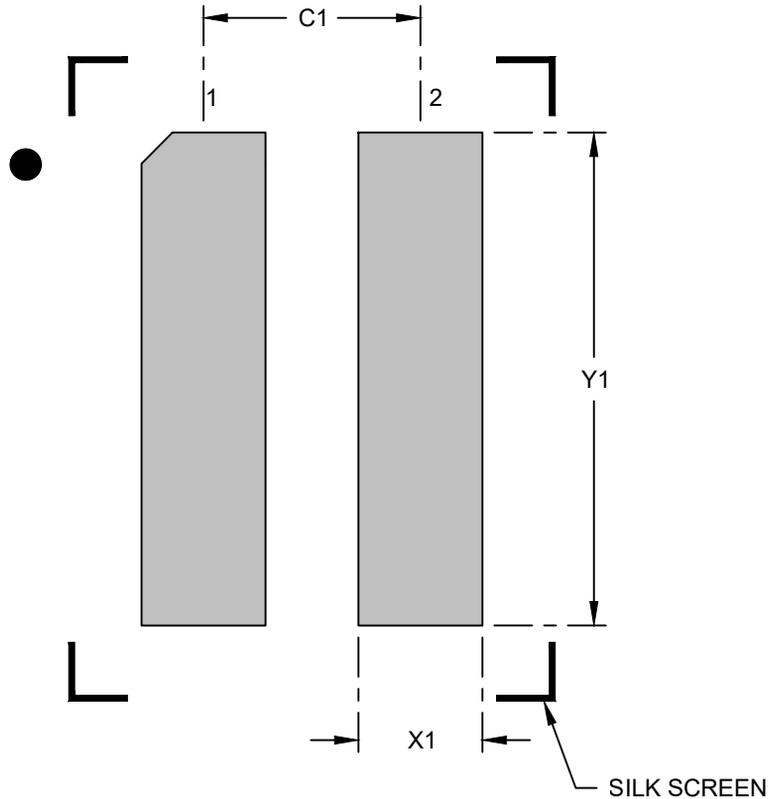


2-Lead Extremely-Thin Single Flatpack No-Leads (9TW) 5x3.5x0.43mm [XSFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pad Spacing	C1		2.10	
Contact Pad Width (X2)	X1			1.20
Contact Pad Length (X2)	Y1			4.75

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. The theoretically exact value is shown without tolerances.
2. For best soldering results, please refer to the current industry standard IPC-7093.